

Title (en)
PROCESS FOR ACTIVATING SUBSTRATES FOR ELECTROLESS PLATING

Publication
EP 0142691 B1 19880921 (DE)

Application
EP 84112030 A 19841008

Priority
DE 3337856 A 19831018

Abstract (en)
[origin: US4568570A] A gentle and inexpensive process for activating surfaces for electroless metallization comprises wetting the surfaces with an activating solution containing a silver-I compound which is sparingly soluble in water (for example AgCl) and which has been converted into a soluble form with the aid of complexing agents (for example NH₃), splitting the soluble complex compound back into the sparingly soluble compound and reducing the silver-I compound remaining on the surface.

IPC 1-7
C23C 18/28

IPC 8 full level
C23C 18/28 (2006.01); **C23C 18/30** (2006.01)

CPC (source: EP US)
C23C 18/28 (2013.01 - EP US)

Cited by
EP2559786B1

Designated contracting state (EPC)
BE CH DE FR GB IT LI NL SE

DOCDB simple family (publication)
EP 0142691 A2 19850529; EP 0142691 A3 19861029; EP 0142691 B1 19880921; CA 1232498 A 19880209; DE 3337856 A1 19850425; DE 3474165 D1 19881027; JP S6096766 A 19850530; US 4568570 A 19860204

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EP 84112030 A 19841008; CA 465497 A 19841016; DE 3337856 A 19831018; DE 3474165 T 19841008; JP 21446584 A 19841015; US 66100784 A 19841015